

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Saxler et al.

Group Art Unit: 2823

Serial No.: 10/617,843

Examiner: Fernando L. Toledo

Filed: July 11, 2003

Confirmation No.: 7985

For:

NITRIDE-BASED TRANSISTORS AND METHODS OF FABRICATION THEREOF

USING NON-ETCHED CONTACT RECESSES

Date: July 8, 2004

Commissioner for Patents P.O. Box 1450

Alexandria, VA 22313-1450

FIFTH INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. § 1.97(b)

Sir:

Attached is a list of documents on Form PTO-1449, together with a copy of any listed foreign patent document and/or non-patent literature. A copy of any listed U.S. patent and/or U.S. patent application publication is not provided herewith in accordance with the waiver by the U.S. Patent and Trademark Office of requirements under 37 C.F.R. § 1.98(a)(2)(i) for all U.S. national patent applications filed after June 30, 2003 and for all international applications that have entered the national stage under 35 USC § 371 after June 30, 2003.

It is requested that these documents be considered by the Examiner and officially made of record in accordance with the provisions of 37 C.F.R. § 1.56 and Section 609 of the MPEP. No fee is believed due. However, the Commissioner is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account No. 50-0220.

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FORM PTO-1449 U.S. Department of Commerce

Patent and Trademark Office

Attorney Docket Number: 5308-248

Serial No.: 10/617,843

LIST OF DOCUMENTS CITED BY APPL

(Use several sheets if necessary)

plicants:

Saxler et al.

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Group: 2823

U. S. PATENT DOCUMENTS

JUL 1 2 2004

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	1.	6,586,781 B2	7/1/03	Wu et al.	257	194	
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	3.	6,515,316 B1	2/4/03	Wojtowicz	257	194	
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	13.	2003/0102482 A1	6/5/03	Saxler	257	85	
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- Burm et al., "Recessed Gate GaN MODFETS", Solid State Electronics, Volume 41, No. 2, pp. 247-250, 1997 22.
- 23. Chen et al., "Reactive ion etching for gate recessing of AlGaN/GaN Field-effect transistors", J. Vac. Sci. Technol. B 17(6), Nov/Dec 1999

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	25.	Karmalkar et al., "Enhancement of Breakdown Voltage in AlGaN/GaN High Electron Mobility Transistors Using a Field Plate, IEEE Transactions on Electron Devices, Vol. 48, No. 8, August 2001						
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	27.	Kuzmik et al. "Annealing of Schottky contacts deposited on dry etched A1GaN/GaN," Semiconductor Science and Technology. Vol. 17, No. 11, November 2002.						
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